



100% Material Declaration Data Sheet BG225

PK143 (v1.2.1) January 8, 2007

Material Declaration Data Sheet

Average Weight: 2.599 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0735	2.83%
	Silicon	7440-21-3	100.00		0.0735	
Die Attach Material					0.0073	0.28%
	Resin	Trade Secret	22.00		0.0016	
	Silver	7440-22-4	78.00		0.0057	
Mold Compound					1.0846	41.73%
	Resin	Trade Secret	12.00		0.1302	
	Silica	60676-86-0	88.00	Filler	0.9544	
Laminate					1.1403	43.87%
	Laminate	Trade Secret		Metal Layer	0.5613	
	Solder Mask (EP)	Trade Secret			0.0878	
	Copper	7440-50-8		Metal Layer	0.4662	
	Nickel	7440-02-0		Metal Layer	0.0209	
	Gold	7440-57-5		Metal Layer	0.0041	
Gold Wire					0.0117	0.45%
	Gold	7440-57-5	100.00		0.0118	
Solder Balls					0.2816	10.83%
	Tin	7440-31-5	63.00		0.1774	
	Lead	7439-92-1	37.00		0.1042	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
7/12/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
1/8/07	1.2.1	Corrected Gold Wire CAS# entry.